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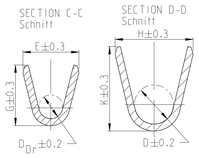
REVISIONS					
F	LTR	DESCRIPTION	DATE	DWN	APVD
	A13	Part status changed	19NOV13	Ho.	Eder
	A14	New Creo drawing created	25APR2014	Ho.	Eder
	A15	Material of PN 928810-1 corrected	26MAY2014	Gitch	Eder
	A16	Add PN´s in the Table	25NOV2014	Ho.	Eder

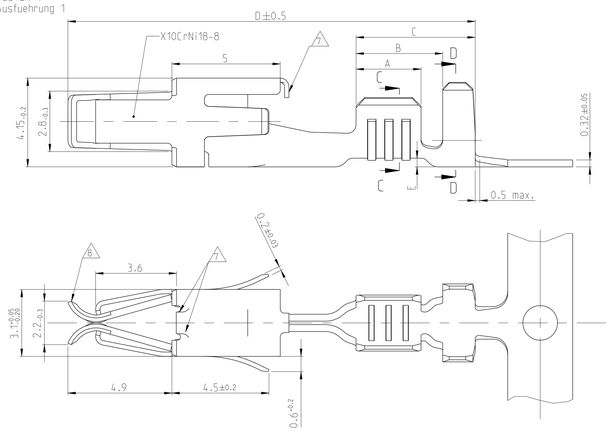


	965901-1 (12)	A	1	CuSn4	PRETINNED vorverzinnt min.0.8µm	0.5-1.0 FLR	1.4-2.3	E = 2.6 G = 2.8 D_{Dr} = 1.1	H = 3.6 K = 3.9 D = 1.8	3	4	5.5	18.8	0.4
	965899-1 (12)	A	1	CuSn4	PRETINNED vorverzinnt min.0.8µm	>1.0-2.5 FLR	2.1-3.1	E = 3.6 G = 3.8 D_{Dr} = 1.8	H = 4.7 K = 4.9 D = 2.6	3.3	4.3	5.8	18.8	0.4
	928876-1	A	1	CuSn4	PLAIN BLANK	0.5-1.0 FLK	2.0-2.7	E = 2.6 G = 2.8 D_{Dr} = 1.1	H = 3.9 K = 4.1 D = 2.4	3	4	5.5	18.8	0.4
	927775-7	M	1	CuNi12ZN24	PRETINNED vorverzinnt min.0.8µm	0.5-1.0 FLK	2.0-2.7	E = 2.6 G = 2.8 D_{Dr} = 1.1	H = 3.9 K = 4.1 D = 2.4	3	4	5.5	18.8	0.4
	927775-6	M		CuSn4	(1)									
	927775-3	M		CuSn4	PRETINNED vorverzinnt min. 0.8µm									
	927775-1	M		CuFe2	PRETINNED vorverzinnt min. 0.8µm									
A15	928810-1 (9)	A	1	CuFe2	PRETINNED vorverzinnt min. 1µm	0.5-1.0 FLR	1.4-2.3	E = 2.6 G = 2.8 D_{Dr} = 1.1	H = 3.6 K = 3.9 D = 1.8	3.0	4.0	5.5	18.8	0.4
	963884-1 (9)	A	1	CuSn4	PRETINNED vorverzinnt min. 1µm	>1.0-2.5 FLR	2.1-3.1	E = 3.6 G = 3.8 D_{Dr} = 1.8	H = 4.7 K = 4.9 D = 2.6	3.3	4.3	5.8	18.8	0.4
	927773-3	N	1	CuSn4	PRETINNED vorverzinnt min. 1µm	>1.0-2.5 FLK	2.7-4.1	E = 3.6 G = 3.8 D_{Dr} = 1.8	H = 5.5 K = 5.8 D = 3.6	3.3	4.3	5.8	18.8	0.4
	927773-1	N		CuFe2										
UNSEALED / ungedichtet	2-927768-1	R	1	CuSn4	(2)	>1.0-2.5 FLR	2.1-3.1	E = 3.6 G = 3.8 D_{Dr} = 1.8	H = 4.7 K = 4.9 D = 2.6	3.3	4.3	5.8	18.8	0.4
	1-927768-1	R		CuFe2										
	927768-9	P		CuSn4	(3) (4)									
	927768-6	P			(1)									
	927768-3	P			PRETINNED vorverzinnt min. 1µm									
	927768-1	P		CuFe2										
	1719810-1 (10)	A	1											
	2-927771-2	N	1	CuSn4	(3) (6)	0.5-1.0 FLR	1.4-2.3	E = 2.6 G = 2.8 D_{Dr} = 1.1	H = 3.6 K = 3.9 D = 1.8	3	4	5.5	18.8	0.4
	2-927771-1	N			(2)									
	1-927771-1	N		CuFe2										
	927771-9	M		CuSn4	(3) (4)									
	927771-8	N			(3) (5)									
	927771-6	M			(1)									
	927771-3	M			PRETINNED vorverzinnt min. 1µm									
	927771-1	M		CuFe2										
	2-927774-1	C	2	CuSn4	(2)	0.2-0.5 FLR	1.0-1.6	E = 2.1 G = 2.1 D_{Dr} = 0.8	H = 2.7 K = 2.8 D = 1.4	2.5	3.5	5.6	18.8	0.4
	1-927774-1	C		CuFe2										
	927774-6	B		CuSn4	(1)									
	927774-3	B			PRETINNED vorverzinnt min. 1µm									
	927774-1	B		CuFe2										
	963708-1	B	2	CuFe2	PRETINNED vorverzinnt min. 1µm	0.08-0.2 Sonderleitung	1.5-1.8	E = 1.7 G = 1.7 D_{Dr} = 0.6	H = 3.1 K = 3.2 D = 1.6	2.5	3.7	5.9	18.8	0.4
	969137-1 (12)	A	3	CuSn4	PRETINNED vorverzinnt min.0.8µm	0.2-0.5 FLR	1.2-2.3	E = 2.1 G = 2.1 D_{Dr} = 0.8	H = 3.5 K = 3.6 D = 2	2.5	3.5	5	18.8	0.4
	1-927778-1	D	3	CuFe2	(2)	0.2-0.5 FLK	1.2-2.3	E = 2.1 G = 2.1 D_{Dr} = 0.8	H = 3.5 K = 3.6 D = 2.0	2.5	3.5	5	18.8	0.4
	927778-3	C		CuSn4	PRETINNED vorverzinnt min.0.8µm									
	927778-1	C		CuFe2										
	2112132-1 (13)	A	4	CuSn4	PLAIN BLANK	0.2-0.5 FLR	1.15-1.6	E = 2.4 G = 2.3 D_{Dr} = 1	H = 2.9 K = 2.9 D = 1.4	2.5	3.5	5.6	18.8	0.2
SINGLE WIRE SEAL / Einzeldichtungssystem	2-927766-1	E	5	CuSn4	(2)	>1.0-2.5 FLK	2.7-3.0	E = 3.6 G = 3.8 D_{Dr} = 1.8	H = 5.4 K = 4.6 D = 3.2	3.5	5.9	7.5	18.8	0.4
	1-927766-1	E		CuFe2										
	927766-3	D		CuSn4	PRETINNED vorverzinnt min. 1µm									
	927766-1	D		CuFe2										
(11)	2-929937-1	E	5	CuSn4	(2)	>1.0-2.5 FLR	2.7-3.0	E = 3.6 G = 3.8 D_{Dr} = 1.8	H = 5.4 K = 4.6 D = 3.2	3.5	5.9	7.5	21	0.4
	1-929937-1	E		CuFe2										
	929937-6	E		CuSn4	(1)									
	929937-3	E			PRETINNED vorverzinnt min. 1µm									
	929937-1	E		CuFe2										
	2-929939-1	E	5	CuSn4	(2)	0.5-1.0 FLR	1.4-2.1	E = 2.6 G = 2.8 D_{Dr} = 1.1	H = 5.4 K = 4.6 D = 3.2	3	5.4	7	21	0.6
	1-929939-1	E		CuFe2										
	929939-6	E		CuSn4	(1)									
	929939-3	E			PRETINNED vorverzinnt min. 1µm									
	929939-1	E		CuFe2										
	2-927770-1	G	5	CuSn4	(2)	0.5-1.0 FLR	1.4-2.1	E = 2.6 G = 2.8 D_{Dr} = 1.1	H = 5.4 K = 4.6 D = 3.2	3	5.4	7	18.8	0.6
	1-927770-1	G		CuFe2										
	927770-6	F		CuSn4	(1)									
	927770-3	F			PRETINNED vorverzinnt min. 1µm									
	927770-1	F		CuFe2										
	2-929941-1	E	6	CuSn4	(2)	0.2-0.5 FLR	1.15-1.6	E = 2.1 G = 2.1 D_{Dr} = 0.8	H = 5.4 K = 4.6 D = 3.2	2.5	4.9	6.5	21	0.9
	1-929941-1	E		CuFe2										
	929941-6	D		CuSn4	(1)									
	929941-3	D			PRETINNED vorverzinnt min. 1µm									
	929941-1	D		CuFe2										
	1-927772-1	D	6	CuFe2	(2)	0.2-0.5 FLR	1.15-1.6	E = 2.1 G = 2.1 D_{Dr} = 0.8	H = 5.4 K = 4.6 D = 3.2	2.5	4.9	6.5	18.8	0.9
	927772-3	C		CuSn4	PRETINNED vorverzinnt min. 1µm									
	927772-1	C		CuFe2										
	TE ORDER NO. / STRIP FORM Bandware	REV.	DESIGN Ausfuehrung	MATERIAL Werkstoff	SURFACE Oberflaeche	WIRE RANGE Drahtgroessen Bereich [mm²]	INSULATION Isolations Ø [mm]	STRIP FORM WIRE CRIMP Drahtcrimp / INSUL.-CRIMP Iso.-Crimp Bandware — CRIMP DIMENSION (mm) Crimpabmessungen (mm)		A	B	C	D	E

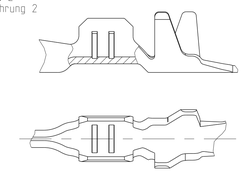
SEE APPLICATION - SPECIFICATION siehe Verarbeitungsspezifikation 114-18050

CRIMP DATA AND CRIMP TOOL Crimpdaten u. Crimpwerkzeuge

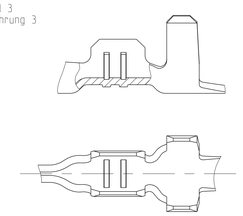
DESIGN 1
Ausfuehrung 1



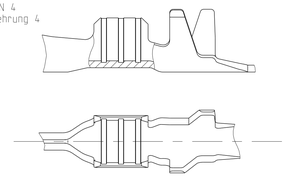
DESIGN 2
Ausfuehrung 2



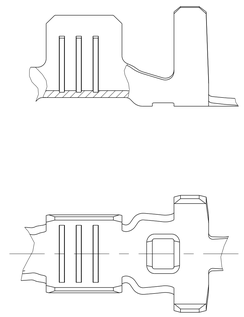
DESIGN 3
Ausfuehrung 3



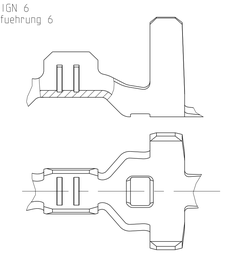
DESIGN 4
Ausfuehrung 4



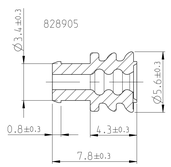
DESIGN 5
Ausfuehrung 5

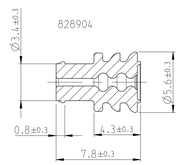


DESIGN 6
Ausfuehrung 6

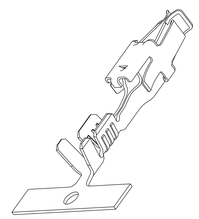


SINGLE WIRE SEAL Einzel-Dichtung (11)		
828904-1	1.2-2.1	blue blau
828905-1	2.2-3.0	white weiss
ORDER No. Bestell-Nr.	INSULATION Ø Isolations Ø	COLOUR Farbe





5:1



NOTES
Bemerkungen

(1) CONTACT BODY PRE-SILVER PLATED MIN. 0.8µm
Kontaktkoerper vorversilbert min. 0.8µm
CONTACT ZONE SELECTIVE PRE-SILVER PLATED MIN. 3µm
Kontaktzone selektiv vorversilbert min. 3µm

(2) CONTACT ZONE GOLD PLATED MIN. 0.8µm OVER MIN. 1.3µm NICKEL-LAYER
Kontaktzone vergoldet min. 0.8µm ueber min. 1.3µm Nickel-Zwischenschicht
CRIMP AREA MIN.1µm TIN PLATED OVER NICKEL-LAYER
Crimpbereich min. 1µm verzinnt ueber Nickel-Zwischenschicht

(3) CANTILEVER SPRING INSIDE AND OUTSIDE 0.4-1.2µm GOLD PLATED
Ueberfeder innen und aussen 0.4-1.2µm vergoldet

(4) CONTACT BODY. CONTACT SPRING INSIDE AND CRIMP AREA MIN. 1µm TIN PLATED OVER NICKEL-LAYER.
TOUCHING AREA TO CANTILEVER SPRING AND CONTACT SPRING OUTSIDE
SELECTIVE 0.8µm GOLD OVER MIN. 1.3µm NICKEL-LAYER
Kontaktkoerper, Kontaktfeder innen und Crimpbereich min. 1.3µm verzinnt
ueber Nickel-Zwischenschicht, Anlageflaeche zur Ueberfeder und Kontaktfeder aussen
selektiv 0.8µm vergoldet ueber min. 1µm Nickel-Zwischenschicht

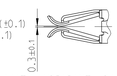
(5) CONTACT ZONE AND TOUCHING AREA TO CANTILEVER SPRING MIN. 0.8µm
SELECTIVE GOLD PLATED OVER
1.3µm NICKEL PLATED. CRIMP AREA MIN. 1µm TIN PLATED OVER NICKEL-LAYER
Kontaktzone und Anlageflaeche zur Ueberfeder min. 0.8µm vergoldet ueber
min. 1.3µm Nickel-Zwischenschicht Crimpbereich min. 1µm verzinnt ueber Nickel-Zwischenschicht

(6) CONTACT BODY AND CRIMP AREA MIN. 1µm TIN PLATED OVER NICKEL-LAYER.
TOUCHING AREA TO CANTILEVER SPRING SELECTIVE 0.8µm GOLD OVER MIN. 1.3µm NICKEL-LAYER
Kontaktkoerper und Crimpbereich min. 1µm verzinnt ueber Nickel-Zwischenschicht
Anlageflaeche zur Ueberfeder selektiv 0.8µm vergoldet ueber min. 1.3µm Nickel-Zwischenschicht

(7) CONTACT OFF OPTIONAL
Abschnitt\Freischnitt optional

(8) SAWAG ONLY FOR PN 929937,929939, 929941
Swage nur fuer PN 929937, 929939, 929941

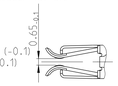
(9) VARIANTS WITH GAP-SIZE 0.3mm (±0.1)
Varianten mit Gap-Size 0.3mm (±0.1)



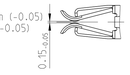
(10) CONTACTS DIPPED IN OR SPRAYED WITH LUBRICANT BARRIERTA
Kontakte getaucht oder besprueht mit Lubricant Barrierta

(11) ACCORDING INSULATION DIA IS TO CHOOSE THE SINGLE WIRE SEAL
Entsprechend dem Isolationsdurchmesser ist die
Einzel-Dichtung auszuwaehlen

(12) VARIANTS WITH GAP-SIZE 0.65mm (-0.1)
Varianten mit Gap-Size 0.65mm (-0.1)



(13) VARIANTS WITH GAP-SIZE 0.15mm (-0.05)
Varianten mit Gap-Size 0.15mm (-0.05)



THIS DRAWING IS A CONTROLLED DOCUMENT.	DWN K. Gerlach 09JUN99 / CHK J. Has 09JUN99	TE Connectivity	
DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED: 1 PLC ±0.2, 2 PLC ±0.1, 3 PLC ±0.05, 4 PLC ±0.02, ANGLES ±4°	APVD –	NAME PRODUCT GROUP DRAWING FOR JUNIOR POWER TIMER CONTACT Produkt-Gruppen-Zeichnung fuer JPT
		PRODUCT SPEC 108-18013	
		APPLICATION SPEC 114-18050	
MATERIAL SEE TABLE	FINISH SEE TABLE	WEIGHT –	SIZE A0 / CAGE CODE 00779 / DRAWING NO C-1355046 / RESTRICTED TO –
–	–	Customer Drawing	SCALE 5:1 / SHEET 1 OF 1 / REV A16